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Substitute for form 1449A/PTO <h2 style="margin: 0;">INFORMATION DISCLOSURE STATEMENT BY APPLICANT</h2> <p style="margin: 10px 0 0 40px;"><i>(use as many sheets as necessary)</i></p>				Complete if Known	
Sheet				Application Number	
1				UNKNOWN 10/666,437	
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				First Named Inventor	
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[illegible]

(Including Author, Title, Date, Pertinent Pages, Etc.)

W2		"Electrodeposition of Copper Thin Film on Ruthenium - A Potential Diffusion Barrier for CU Interconnects", Oliver Chyan et al., Journal of The Electrochemical Society, Volume 150, Number 5 (2003)
W2		"Seedless Superfill: Copper Electrodeposition in Trenches with Ruthenium Barriers", D. Josell et al., Electrochemical and Solid State Letters, June 5, 2003
W2		"Liner Materials for Direct Electrodeposition of Cu", M.W.Lane et al., Applied Physics Letter, Volume 83, Number 12, September 22, 2003
W2		"International Technology Roadmap for Semiconductors", 2001

William Leader 4/18/2007